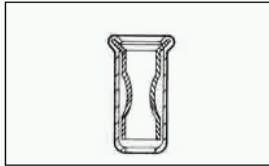


50864-5 Product Details



50864-5

TE Part Number: 50864-5

✓ [Active](#)

 [Add to Part List](#)

Discrete Sockets

[Not EU RoHS or ELV Compliant](#) ([Find RoHS Compliant Alternates](#))

Product Highlights:

- Socket
- Mating Pin Dia. Range = .66 - .84 mm
- Socket Length = 6.53 mm
- Sleeve Style = Open Bottom
- Tin Sleeve Plating

[View all Features](#) | [Find Similar Products](#)

 [Live Product Chat](#)

Quick Links

- ▶ [Check Pricing & Availability](#)
- ▶ [Search for Tooling](#)
- ▶ [Product Feature Selector](#)
- ▶ [Contact Us About This Product](#)
- ▶ [Request Samples](#)

NEW!

Documentation & Additional Information

Product Drawings:

- [MINIATURE SPRING SOCKET ASSEMBLY](#) (PDF, English)

Catalog Pages/Data Sheets:

- None Available

Product Specifications:

- None Available

Application Specifications:

- None Available

Instruction Sheets:

- None Available

CAD Files: ([CAD Format & Compression Information](#))

- [2D Drawing](#) (DXF, Version AD)
- [3D Model](#) (IGES, Version AD)
- [3D Model](#) (STEP, Version AD)

[List all Documents](#)

Additional Information:

- [Product Line Information](#)

Related Products:

- [Tooling](#)

Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- Product Type = Socket
- [Socket Length \(mm \[in\]\)](#) = 6.53 [0.257]
- [Sleeve Style](#) = Open Bottom
- [Sealant](#) = Without
- Sleeve Material = Copper
- Recommended Hole Size (mm [in]) = 1.57 [0.062]

Body Related Features:

- [Mating Pin Dia. Range \(mm \[in\]\)](#) = 0.66 - 0.84 [0.026 - 0.033]
- Spring Material = Beryllium Copper

Contact Related Features:

- [Sleeve Plating](#) = Tin
- [Contact Spring Plating](#) = Gold (30)
- [Contact Material](#) = Beryllium Copper

Configuration Related Features:

- [Insertion Method](#) = Hand/Semi-Automatic/Automatic

Industry Standards:

- Government/Industry Qualification = No
- [RoHS/ELV Compliance](#) = Not ELV/RoHS compliant
- [Lead Free Solder Processes](#) = Wave solder capable to 240°C, Wave solder capable to 260°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C

Operation/Application:

- Application = Production

Packaging Related Features:

- [Packaging Method](#) = Loose Piece

Other:

- Brand = AMP